

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 14 of the application as follows:

ABSTRACT OF THE DISCLOSURE

Flip-chip semiconductor assemblies, each including integrated circuit (IC) dice and an associated substrate, are electrically tested before encapsulation using an in-line or ~~in situ~~ in situ test socket or probes at a die-attach station. Those assemblies using “wet” quick-cure epoxies for die attachment may be tested prior to the epoxy being cured by pressing the integrated circuit (IC) dice against interconnection points on the substrate for electrical connection, while those assemblies using “dry” epoxies may be cured prior to testing. In either case, any failures in the dice or in the interconnections between the dice and the substrates can be easily fixed, and the need for the use of known-good-die (KGD) rework procedures during repair is eliminated.